### Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

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### Assembly Notes

**ZZ1**

*Extra Assembly Note*

*Not necessary fields on PCB labels only*

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**ZZ2**

*Assembly Note*

*These assemblies are ESD sensitive, ESD precautions shall be observed.*

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**ZZ3**

*Assembly Note*

*These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.*

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**ZZ4**

*Assembly Note*

*These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.*
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